

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
-30V	10.5mΩ@-10V	-13.5A
	13mΩ@-4.5V	

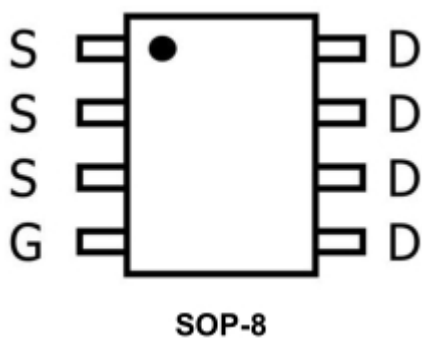
## Feature

- TrenchFET Power MOSFET
- Excellent  $R_{DS(on)}$  and Low Gate Charge

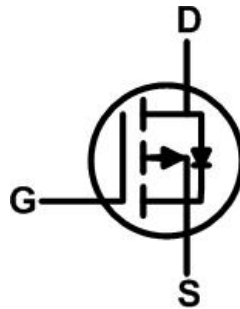
## Applications

- Advanced trench process technology
- High density cell design for ultra-low on-resistance
- High power and current handing capability
- Ideal for Lion battery pack applications

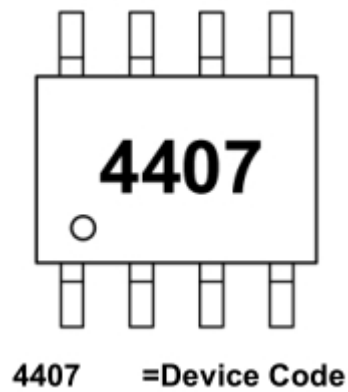
## Package



## Circuit diagram



## Marking



## Absolute maximum ratings

( $T_a=25^{\circ}\text{C}$  unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	-13.5	A
Pulsed Drain Current <sup>1)</sup>	$I_{DM}$	-65	A
Power Dissipation	$P_D$	3	W
Thermal Resistance from Junction to Ambient <sup>2)</sup>	$R_{\theta JA}$	75	$^{\circ}\text{C/W}$
Junction Temperature	$T_J$	150	
Storage Temperature	$T_{STG}$	-55~ +150	$^{\circ}\text{C}$

## Electrical characteristics

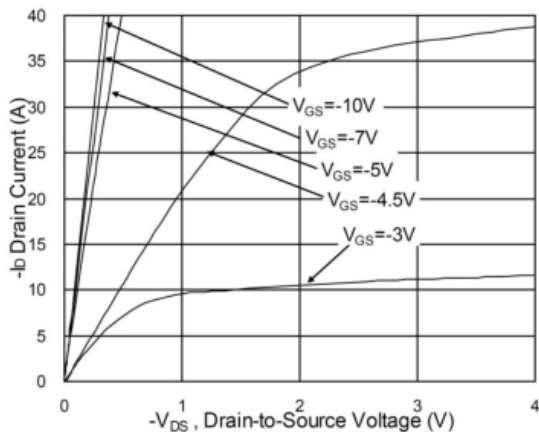
( $T_A=25^{\circ}\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	BV (BR)DSS	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-30			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V			1	uA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	uA
Gate threshold voltage <sup>1)</sup>	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1.0	-1.5	-2.2	V
Drain-source on-resistance <sup>1)</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -12A		10.5	14	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -7A		13	29	
Dynamic Characteristics <sup>4)</sup>						
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -15V, V <sub>GS</sub> =0V, f=1MHz		3448		pF
Output capacitance	C <sub>oss</sub>			508		
Reverse transfer capacitance	C <sub>rss</sub>			421		
Switching Characteristics <sup>4)</sup>						
Turn-on Delay Time	T <sub>d(on)</sub>	V <sub>GS</sub> = -10V, V <sub>DD</sub> = -15V, R <sub>GEN</sub> =3.3Ω, I <sub>D</sub> = -1A		9.4		nS
Turn-on Rise Time	T <sub>r</sub>			10.2		
Turn-Off Delay Time	T <sub>d(off)</sub>			117		
Turn-Off Fall Time	t <sub>f</sub>			24		
Total gate charge	Q <sub>g</sub>	V <sub>DS</sub> = -15V, V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -12A		30		pF
Gate-source charge	Q <sub>gs</sub>			10		
Gate-drain charge	Q <sub>gd</sub>			10.4		
Source-Drain Diode Characteristics						
Body Diode Voltage	V <sub>DS</sub>	I <sub>S</sub> = -1A, V <sub>GS</sub> = 0V			-1.2	V

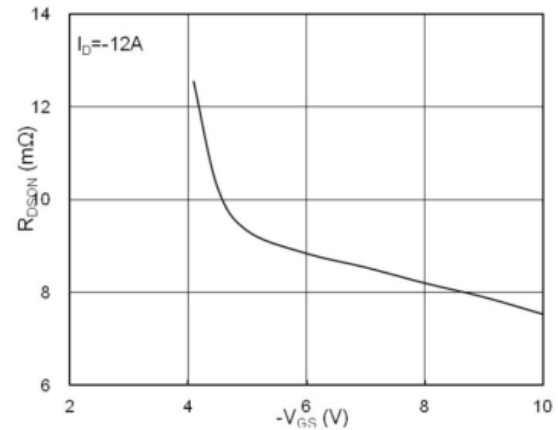
### Notes:

1. Repetitive rating: Pulse width limited by junction temperature.
2. Surface mounted on FR4 board,  $t \leq 10s$ .
3. Pulse Test: Pulse Width  $\leq 80\mu s$ , Duty Cycle  $\leq 0.5\%$ .
4. Guaranteed by design, not subject to producing.

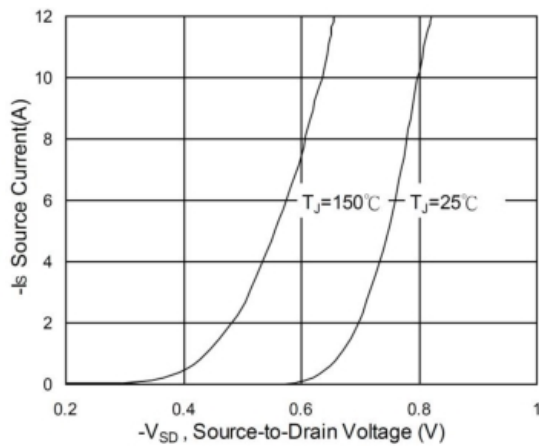
## Typical Characteristics



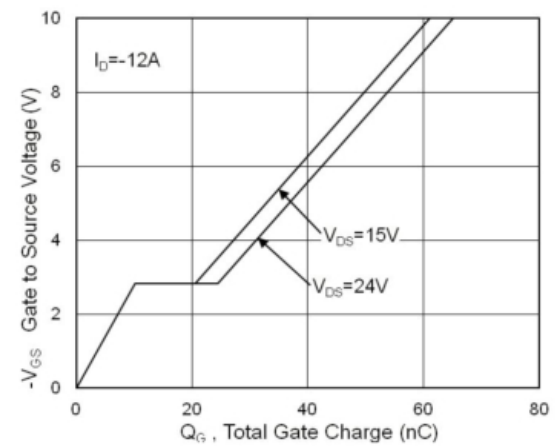
Typical Output Characteristics



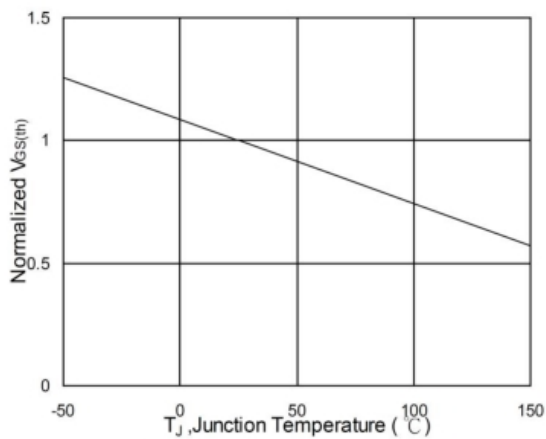
On-Resistance v.s Gate-Source



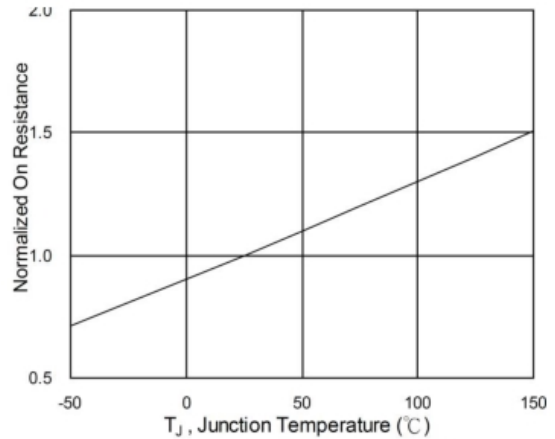
Forward Characteristics Of Reverse



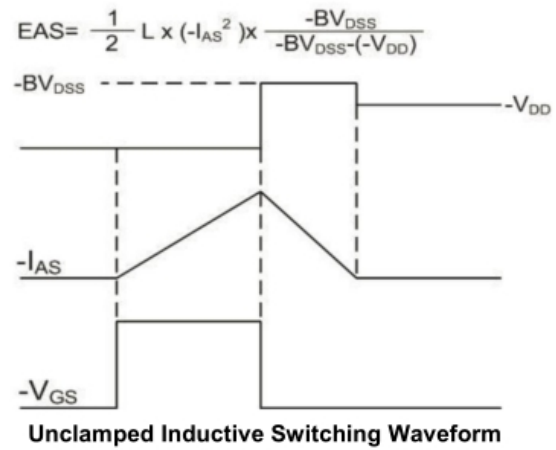
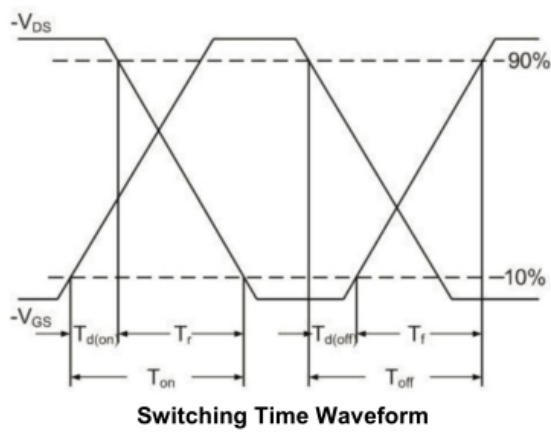
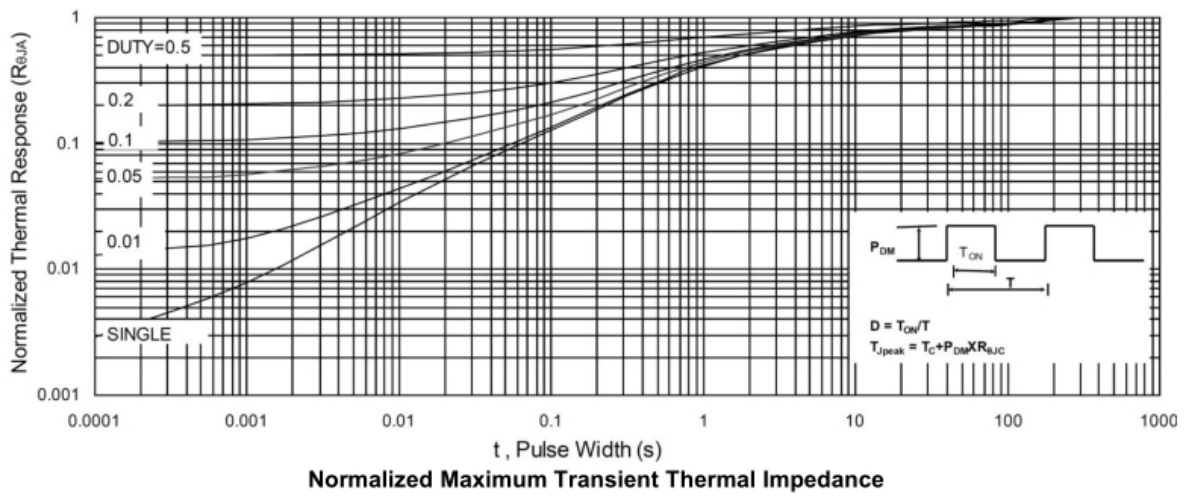
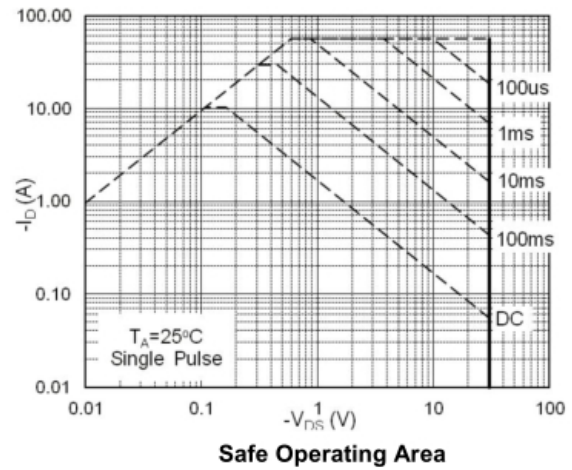
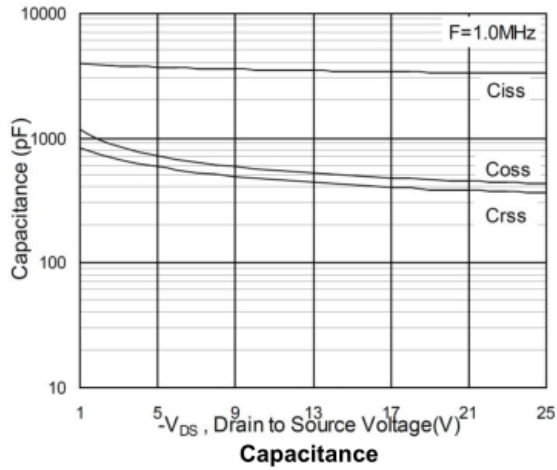
Gate-Charge Characteristics



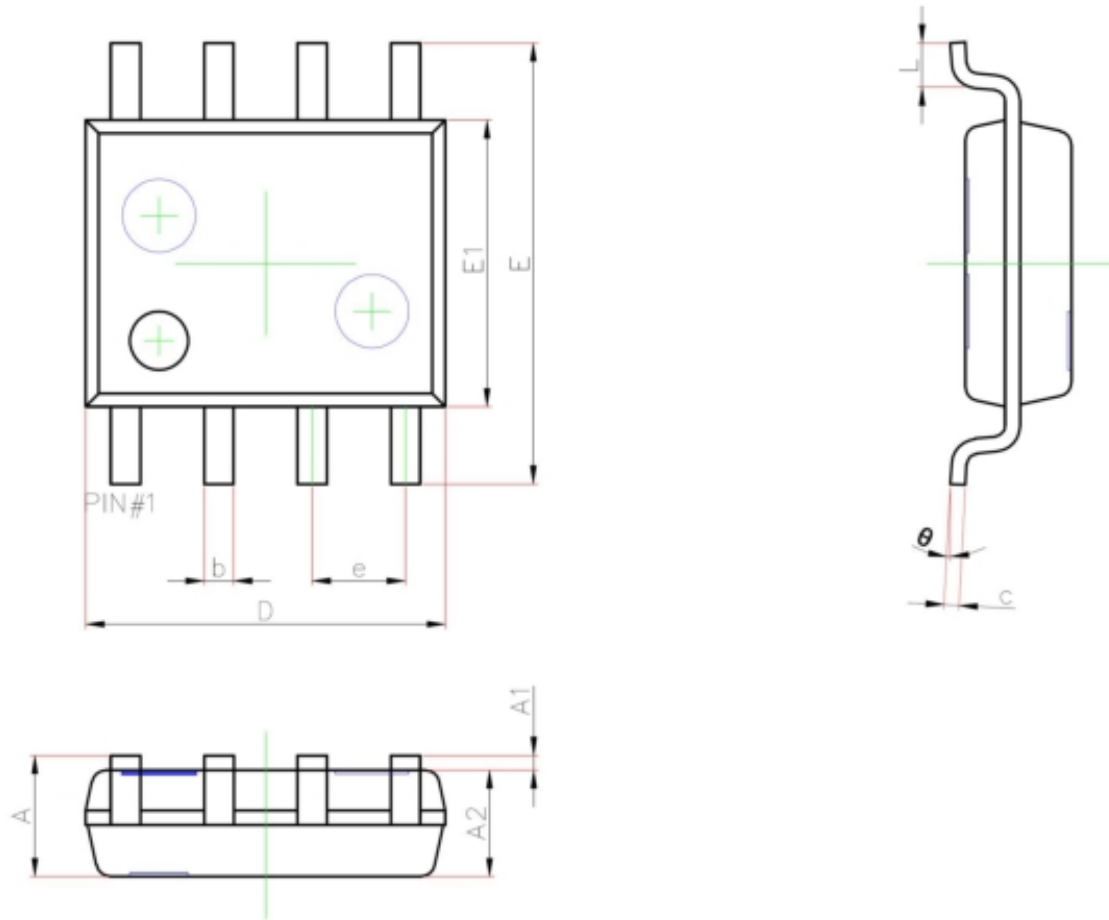
Normalized  $V_{GS(th)}$  vs.  $T_J$



Normalized  $R_{DS(on)}$  vs.  $T_J$



## SOP-8 Package Information



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	1.35	1.75
A1	0.10	0.25
A2	1.35	1.55
b	0.33	0.51
c	0.17	0.25
D	4.80	5.00
e	1.27 REF.	
E	5.80	6.20
E1	3.80	4.00
L	0.40	1.27
$\theta$	0°	8°